

SN54ABT241, SN74ABT241A OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

SCBS184C – JANUARY 1991 – JUNE 1996

- State-of-the-Art *EPIC-II B*™ BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$
- High-Drive Outputs (–32-mA I_{OH} , 64-mA I_{OL})
- Package Options Include Plastic Small-Outline (DW) and Shrink Small-Outline (DB) Packages, Ceramic Chip Carriers (FK), and Plastic (N) and Ceramic (J) DIPs, and Ceramic Flat (W) Packages

description

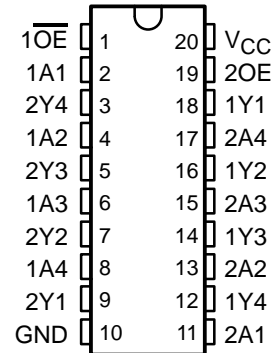
These octal buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. Together with the SN54ABT240, SN74ABT240A and SN54ABT244, SN74ABT244A, these devices provide the choice of selected combinations of inverting and noninverting outputs, symmetrical active-low output-enable (\overline{OE}) inputs, and complementary OE and \overline{OE} inputs.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver. OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

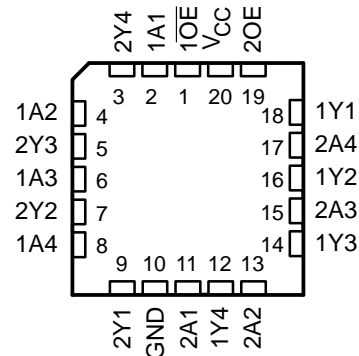
The SN74ABT241A is available in TI's shrink small-outline package, which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54ABT241 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ABT241A is characterized for operation from -40°C to 85°C .

SN54ABT241 . . . J OR W PACKAGE
SN74ABT241A . . . DB, DW, OR N PACKAGE
(TOP VIEW)



SN54ABT241 . . . FK PACKAGE
(TOP VIEW)



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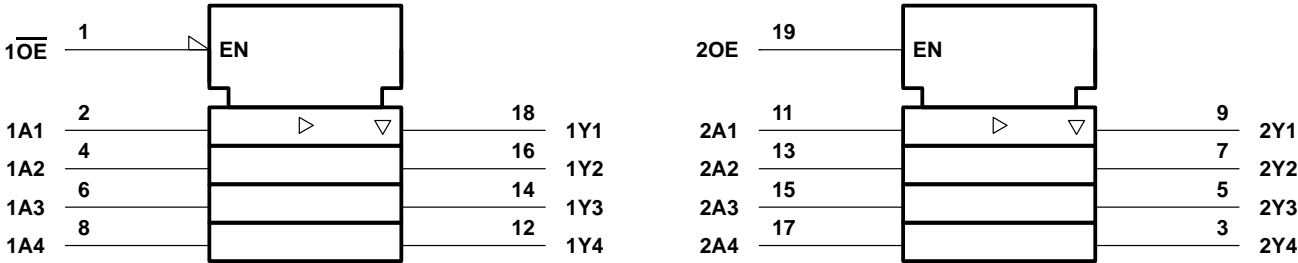
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FUNCTION TABLES

INPUTS		OUTPUT 1Y
1OE	1A	
L	H	H
L	L	L
H	X	Z

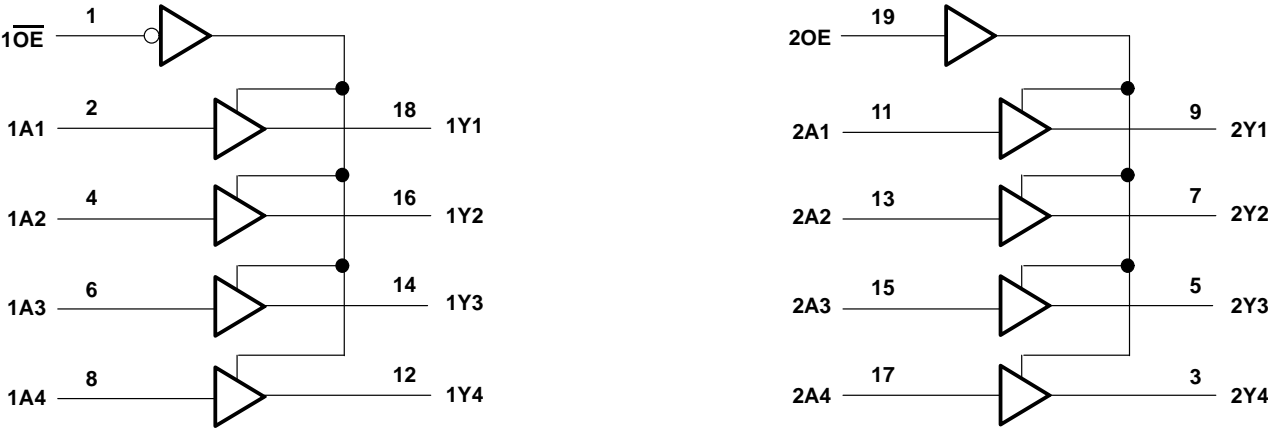
INPUTS		OUTPUT 2Y
2OE	2A	
H	H	H
H	L	L
L	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, V_O	–0.5 V to 5.5 V
Current into any output in the low state, I_O : SN54ABT241	96 mA
SN74ABT241A	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–18 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 2): DB package	0.6 W
DW package	1.6 W
N package	1.3 W
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero. For more information, refer to the *Package Thermal Considerations* application note in the *ABT Advanced BiCMOS Technology Data Book*.

recommended operating conditions (see Note 3)

		SN54ABT241		SN74ABT241A		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–32	mA
I_{OL}	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5	5	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

SN54ABT241, SN74ABT241A

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		T _A = 25°C			SN54ABT241		SN74ABT241A		UNIT
			MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V _{IK}	V _{CC} = 4.5 V, I _I = -18 mA				-1.2		-1.2		-1.2	V
V _{OH}	V _{CC} = 4.5 V, I _{OH} = -3 mA		2.5			2.5		2.5		V
	V _{CC} = 5 V, I _{OH} = -3 mA		3			3		3		
	V _{CC} = 4.5 V	I _{OH} = -24 mA	2			2				
		I _{OH} = -32 mA	2*					2		
V _{OL}	V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			V
		I _{OL} = 64 mA			0.55*				0.55	
I _I	V _{CC} = 5.5 V, V _I = V _{CC} or GND				±1		±1		±1	μA
I _{OZH}	V _{CC} = 5.5 V, V _O = 2.7 V				10		10		10	μA
I _{OZL}	V _{CC} = 5.5 V, V _O = 0.5 V				-10		-10		-10	μA
I _{off}	V _{CC} = 0, V _I or V _O ≤ 4.5 V				±100				±100	μA
I _{CEX}	V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μA
I _{O‡}	V _{CC} = 5.5 V, V _O = 2.5 V		-50	-100	-180	-50	-180	-50	-180	mA
I _{CC}	V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND	Outputs high		1	250		250		250	μA
		Outputs low		24	30		30		30	mA
		Outputs disabled		0.5	250		250		250	μA
ΔI _{CC} §	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND	Data inputs			1.5		1.5		1.5	mA
					0.05		0.05		0.05	
		Control inputs			1.5		1.5		1.5	
C _i	V _I = 2.5 V or 0.5 V			4						pF
C _o	V _O = 2.5 V or 0.5 V			5.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.

† All typical values are at V_{CC} = 5 V.

‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.



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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT241					UNIT
			V _{CC} = 5 V, T _A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t _{PLH}	A	Y	1	2.6	4.1	0.8	5.3	ns
t _{PHL}			1	2.9	4.2	0.8	5	
t _{PZH}	\overline{OE} or OE	Y	1.1	4.8	6.3	1	7	ns
t _{PZL}			1.3	4.3	5.8	1	7	
t _{PHZ}	\overline{OE} or OE	Y	1.1	4.6	6.1	0.8	7.9	ns
t _{PLZ}			1	3.9	5.4	0.8	6.2	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT241A					UNIT
			V _{CC} = 5 V, T _A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t _{PLH}	A	Y	1	2.6	4.1	1	4.6	ns
t _{PHL}			1	2.9	4.4	1	4.6	
t _{PZH}	OE or OE	Y	1.1	4.8	6.3	1.1	6.8	ns
t _{PZL}			1.3	4.3	5.8	1.3	6.8	
t _{PHZ}	OE or OE	Y	1.6	4.6	6.1	1.6	7.1	ns
t _{PLZ}			1	3.9	5.4	1	5.9	

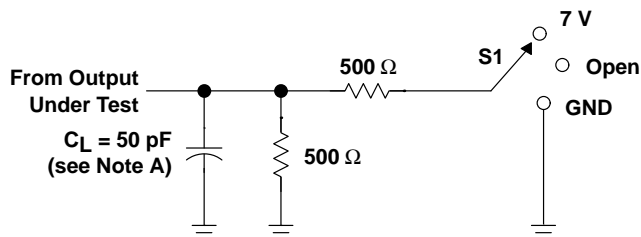
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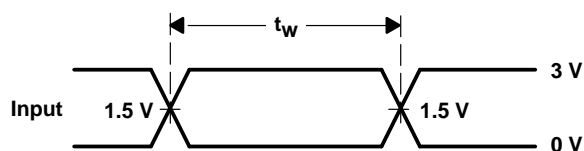
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PARAMETER MEASUREMENT INFORMATION

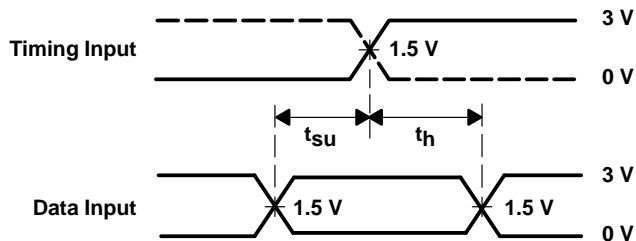


LOAD CIRCUIT

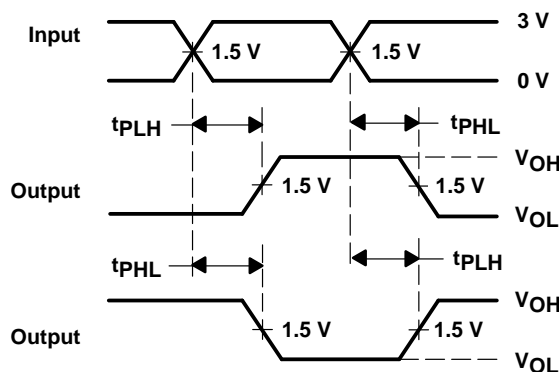
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



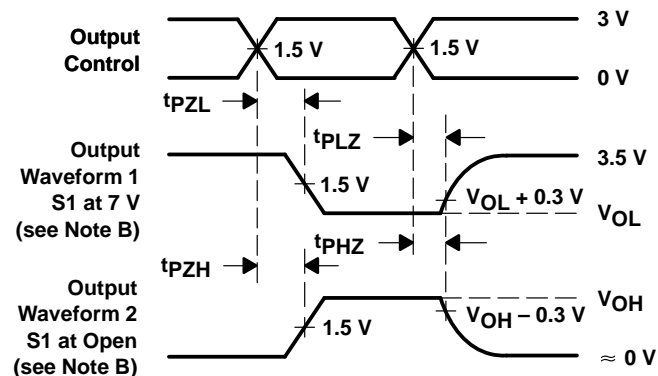
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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